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"Electronics Packaging Forum: Volume 2" (Van Nostrand Reinhold) December 1990. (Vols 1 & 2 now available in one volume from Springer) "Electronics Packaging Forum: Multichip Module Technology Issues" (IEEE Press) January 1994.

BIOGRAPHICAL DATA James Eliot Morris

Based on presentations at the Electronics Packaging Symposium, held at the State University of New York, Binghamton in May 1991, this practical volume provides a multidisciplinary treatment of the field of electronic packaging and multichip modules.

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activity over the last five years, with entire conferences being dedicated to multichip modules. MCMs have gone through three phases in their growth. Phase one was the widespread use in mainframe and super computer products.

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Multichip Modules}, Chapter 7 in Electronics Packaging Forum, Volume 3, J. Morris (ed), 1993 by IEEE

Press. 8. P. Franzon, Comparison of Reconfiguration Schemes for Defect Tolerant Mesh Arrays , in Defect and Fault Tolerance in VLSI Systems, Volume 2, V.K. Jain (editor), (Plenum), 1989. ...

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